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AMENDMENTS

In the Claims:

Please amend the claims to read as follows:

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1. (Currently Amended) A small footprint semiconductor device package comprising:
a plastic package body for enclosing a die, the plastic package body including a top coupled to a bottom through a plurality of sides;
a diepad supporting the die, the diepad having a first side and a second side opposite the first side;
a first lead integral with a first side of the diepad and in electrical and thermal communication with the die through the diepad, the first lead including an enclosed portion by the package body and in electrical communication with the die, and an exposed portion of the first lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package at a first angle, and folding underneath the package bottom toward a center of the bottom of the package to form a first lead foot, whereupon the portion of the first lead along the side of the package and the portion of the lead along the bottom of the package form an angle of less than 90° from each other and the first lead foot being inclined at a second angle relative to an underlying planar PC board to promote solder wetting; and
a second lead nonintegral with the second side of the diepad and in electrical communication with the die through a bondwire, the second lead including an enclosed portion by the package body and in electrical communication with the die, and an exposed portion of the second lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package at a first angle, and folding underneath the package bottom toward a center of the bottom of the package to form a second lead foot, whereupon the portion of the second lead along the side of the package and the portion of the lead along the bottom of the package form an

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angle of less than 90° from each other and the second lead foot being inclined at a second angle relative to an underlying planar PC board to promote solder wetting.

2. (Original) The package of claim 1 wherein the die is one of a power device, a discrete device, and an integrated circuit.

3. (Original) The package of claim 1 wherein the lead forms a reverse gull wing shape.

4. (Previously Amended) The package of claim 1 wherein the package has a reduced package profile including the lead.

5. (Original) The package of claim 1 wherein the lead foot is inclined at the second angle between 1° and 7° relative to the planar PC board.

6. (Original) The package of claim 1 wherein the package body further comprises a notch configured to receive a portion of the lead foot, thereby permitting the lead foot to be partially recessed within the package body in order to reduce a height of the package.

7. (Currently Amended) The package of claim 4 6 wherein the notch includes a depth of about two-thirds a thickness of the lead.

Claims 8-12 (Withdrawn).

Claims 13-15 (Canceled).